

# ophellia

**Optical gain via multilayer monolithic  
integration of  $\text{Si}_3\text{N}_4$  with  $\text{Al}_2\text{O}_3:\text{Er}^{3+}$   
waveguide amplifiers**

*ECIO Integrated photonic technologies and platforms – 20<sup>th</sup> April 2023*

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**UNIVERSITY  
OF TWENTE.**

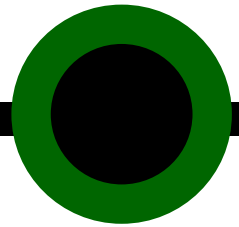
**MESA+**  
INSTITUTE FOR NANOTECHNOLOGY

**i@S**  
INTEGRATED OPTICAL SYSTEMS

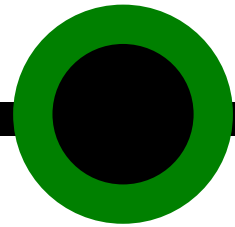
<https://lidar-ophellia.eu>



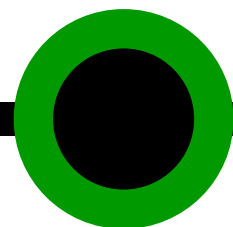
# Content



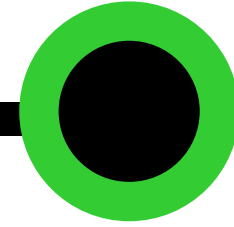
Introduction



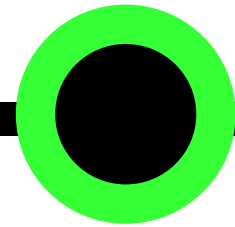
$\text{Al}_2\text{O}_3$  as photonic platform



Monolithic integration with  $\text{Si}_3\text{N}_4$



EDWA measurements



Summary



- Develop novel materials and integration technologies for laser sources for LiDAR applications.
- **Low cost, low size** and **lightweight** → high **chip integration** and **tolerant packaging** technology.

Photonic Integrated Circuits (PICs) are **essential** to achieve this goal

**TOF Source:**

**FMCW Source:**

**Demonstrators:**

**Demo1:** Sensor Intelligence.

- Safety in harbors and airports
- Industry 4.0

**Demo2:**

- Autonomous robots/drones
- Industrial environments

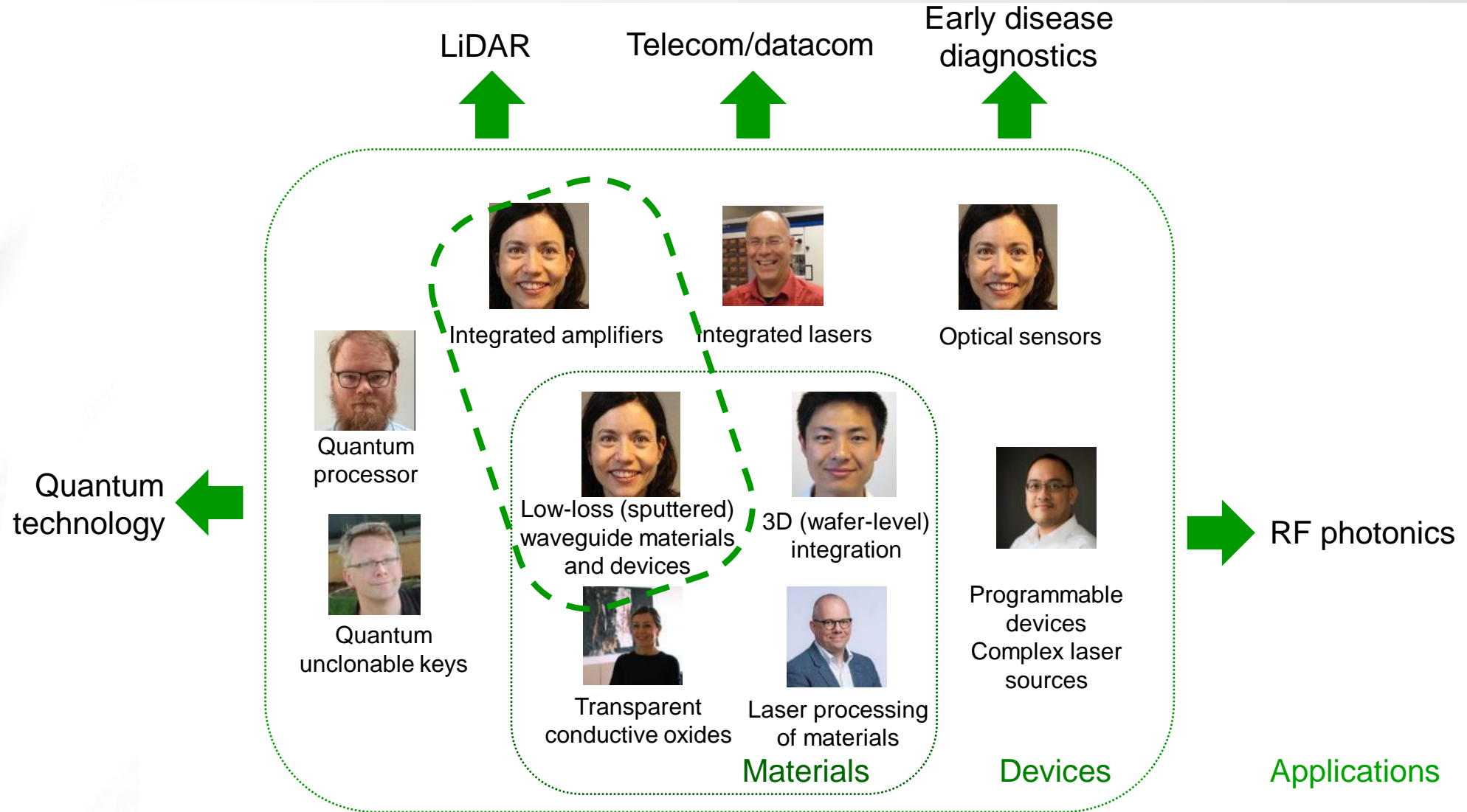
**Demo3:**

- Autonomous trains
- Safety

**Other application fields for OPHELLIA PICs:**

Exploration of photonics markets

PIC/packaging partners:



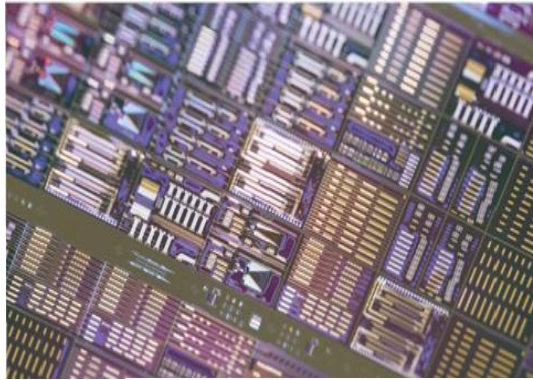




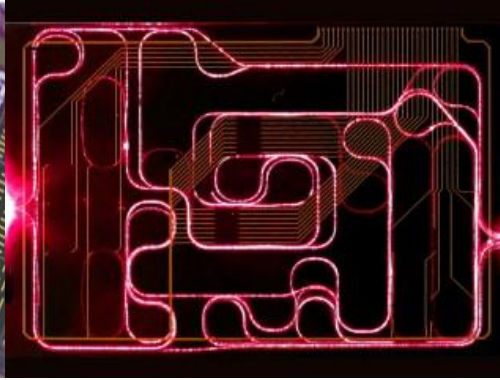
- 1250 m<sup>2</sup> cleanroom
- 1000 m<sup>2</sup> for specialized equipment
- Deposition (PVD + CVD), lithography, E-beam, etching, dicing, SEM, TEM, XRD, annealing etc.



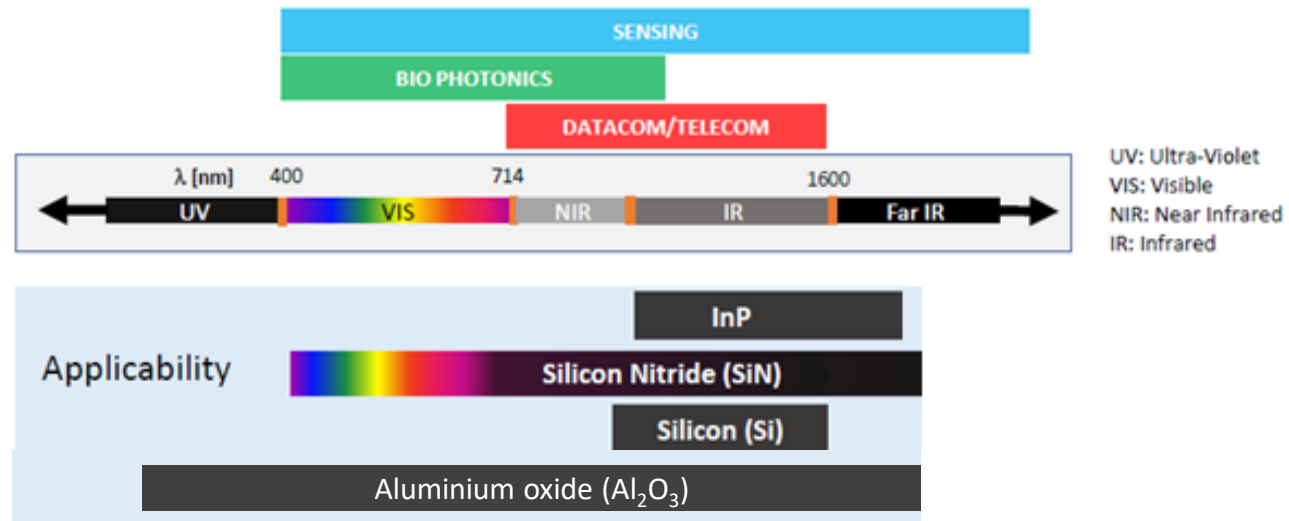
InP



SiN

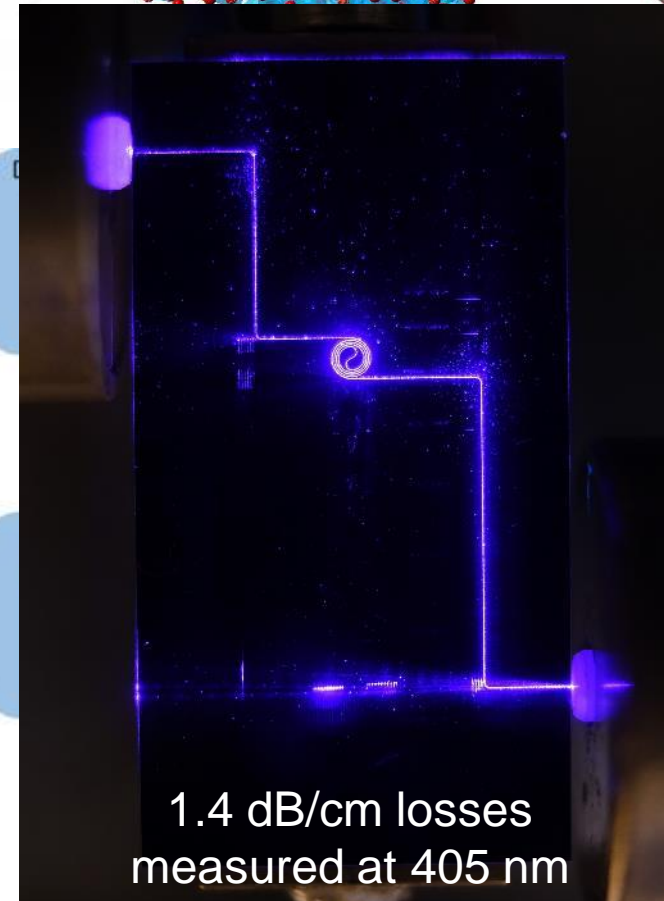
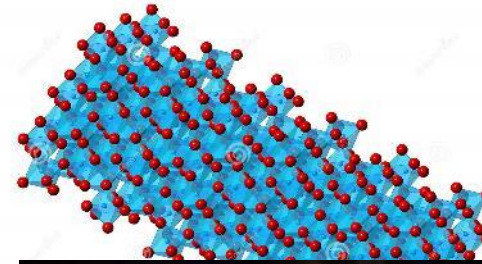


Si

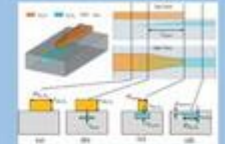




- Naturally occurring in crystalline state as corundum, forming popular gems such as ruby and sapphire
- Large transparency window: UV-mid-IR
- Low propagation losses: 5 dB/m
- Moderate refractive index: ~1.72 @1550 nm
- Wafer level deposition
- High rare-earth ion solubility
- In the Nanolab → RF reactive sputtering



Monolithic integration

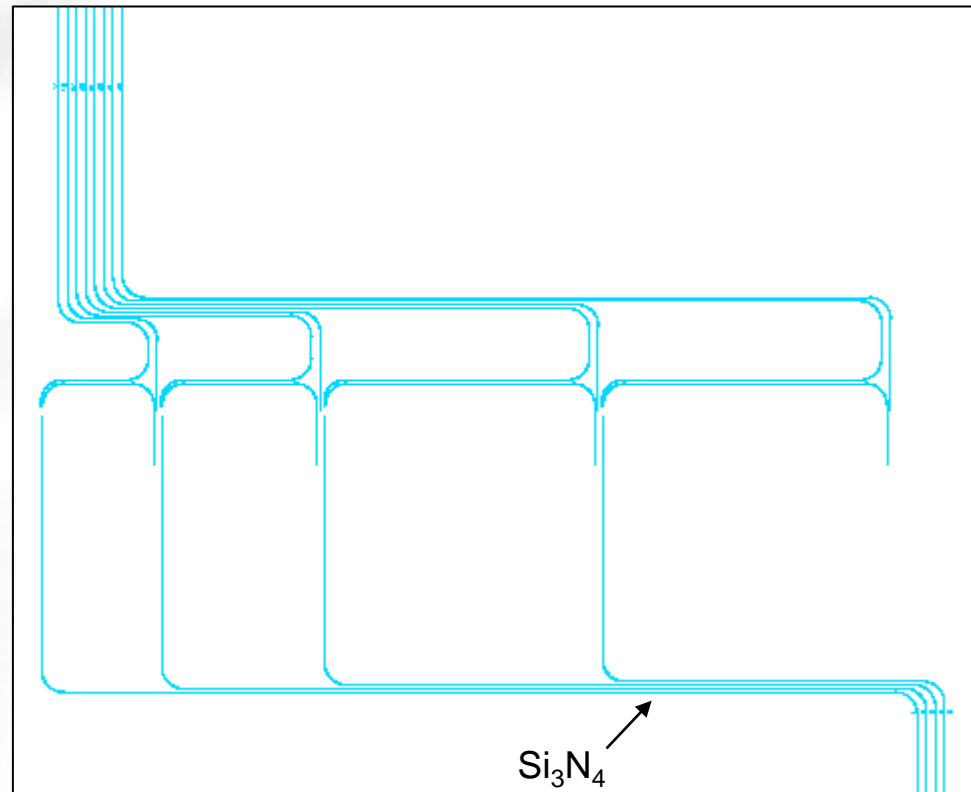


On-chip amplifiers

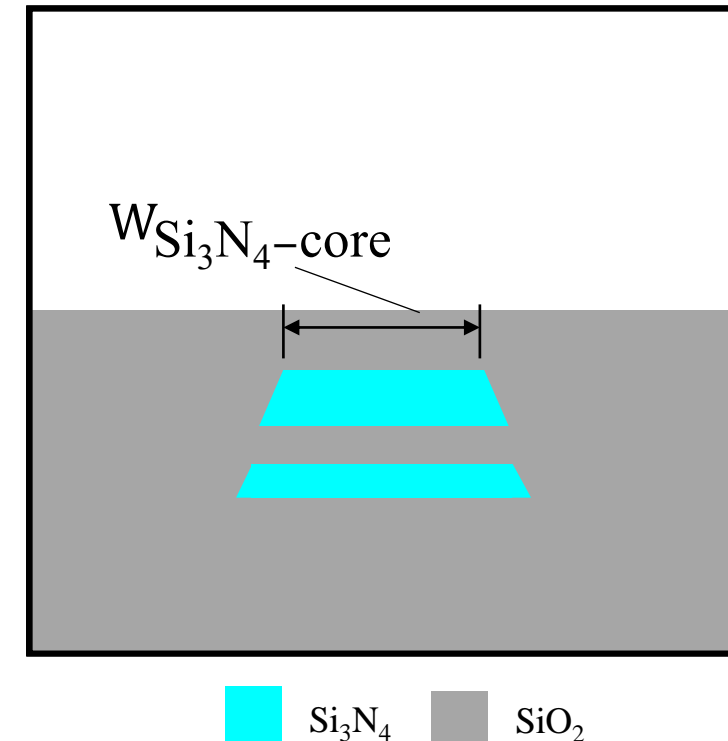


21)

- Chip layout and building blocks
  - Si<sub>3</sub>N<sub>4</sub> TriPleX input/output couplers
  - 50/50 splitter
  - Reference branch

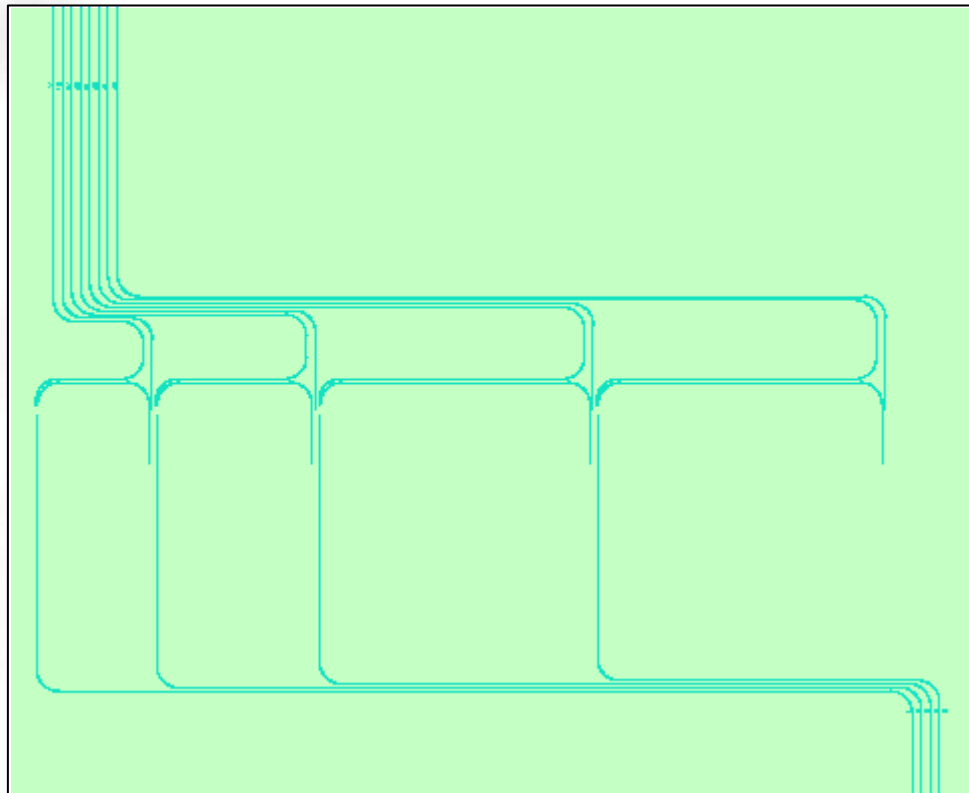


Cross-section

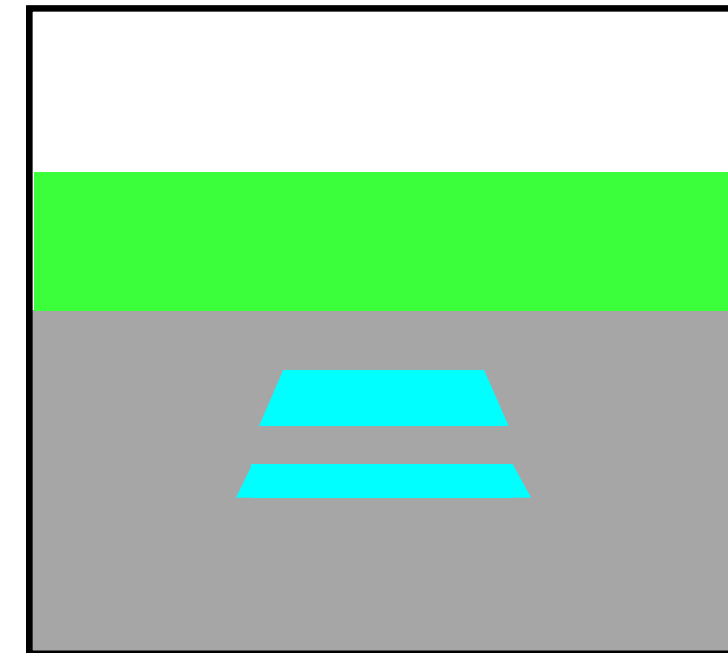




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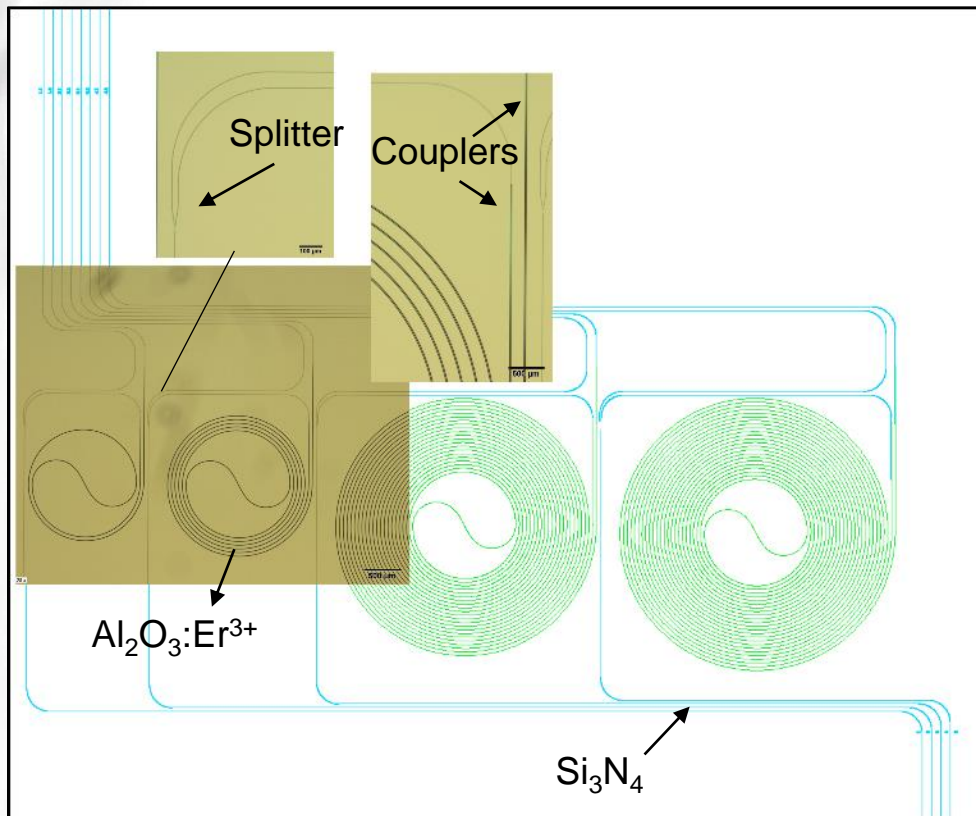


Cross-section

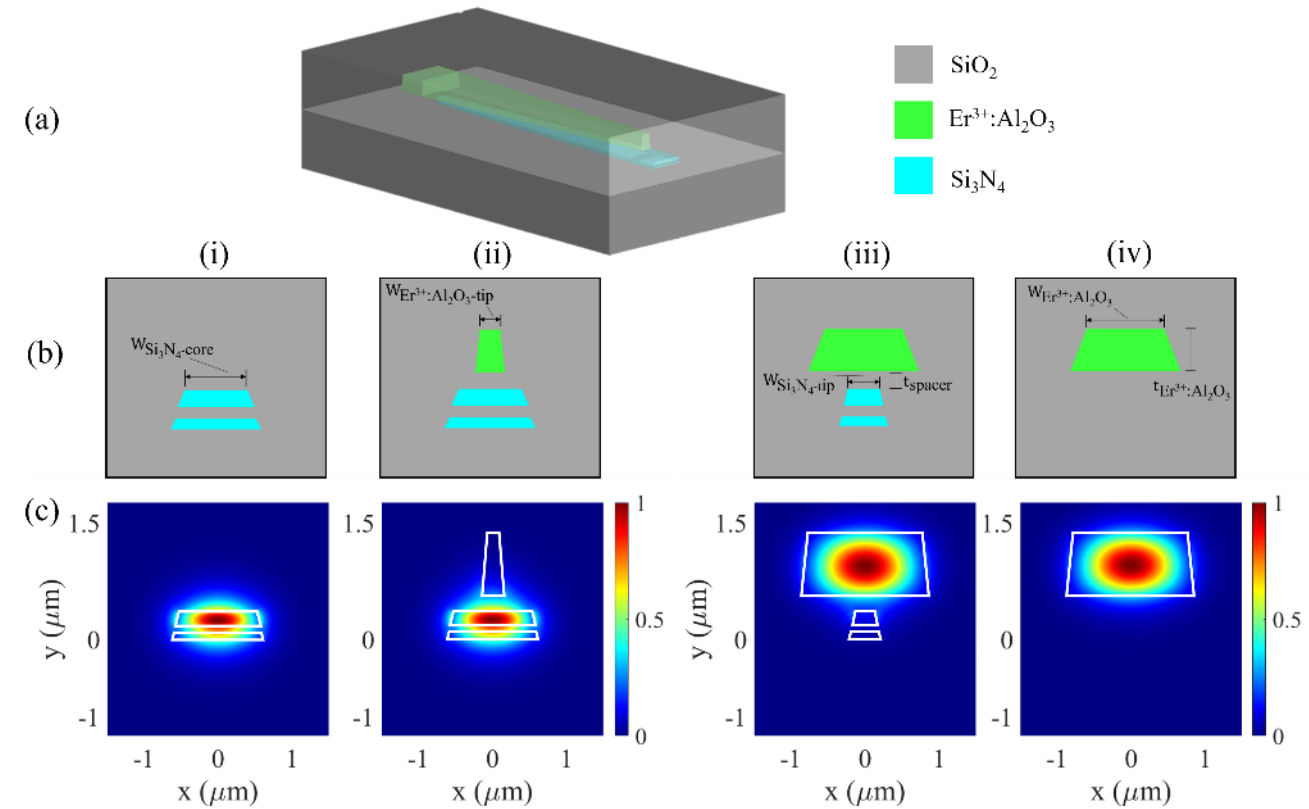


Er<sup>3+</sup>:Al<sub>2</sub>O<sub>3</sub>
 Si<sub>3</sub>N<sub>4</sub>
 SiO<sub>2</sub>

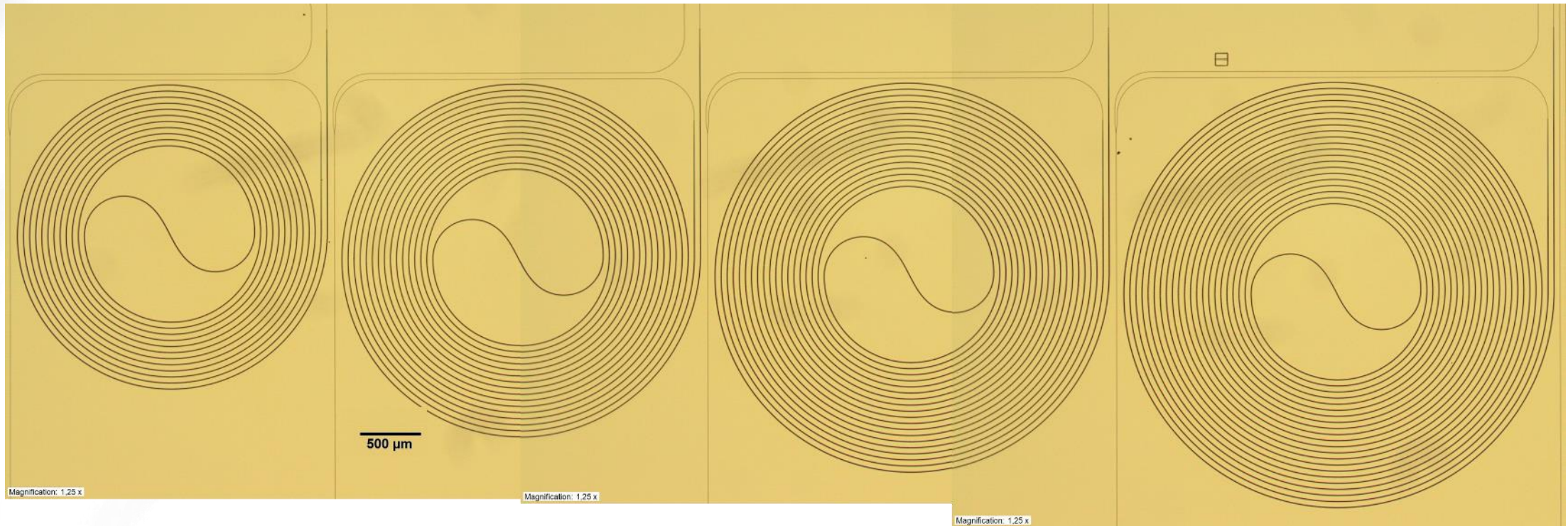
- Chip layout and building blocks
  - Si<sub>3</sub>N<sub>4</sub> TriPleX input/output couplers
  - 50/50 splitter
  - Reference branch
  - Si<sub>3</sub>N<sub>4</sub> – Al<sub>2</sub>O<sub>3</sub> coupler + **amplifier**



## Vertical adiabatic taper – Passive / Active coupling

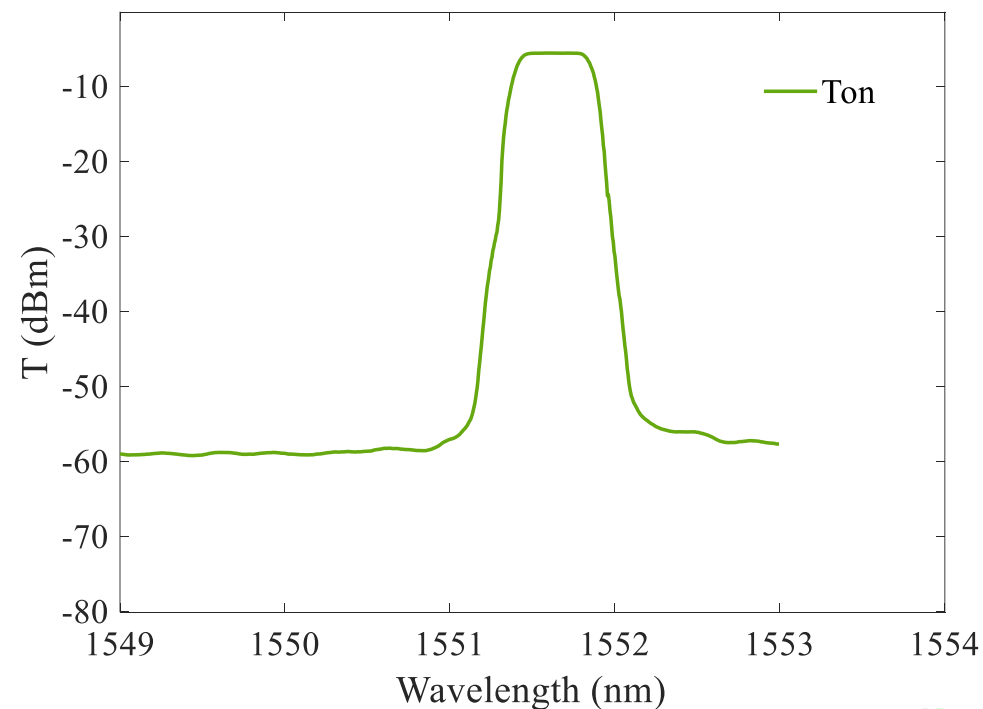
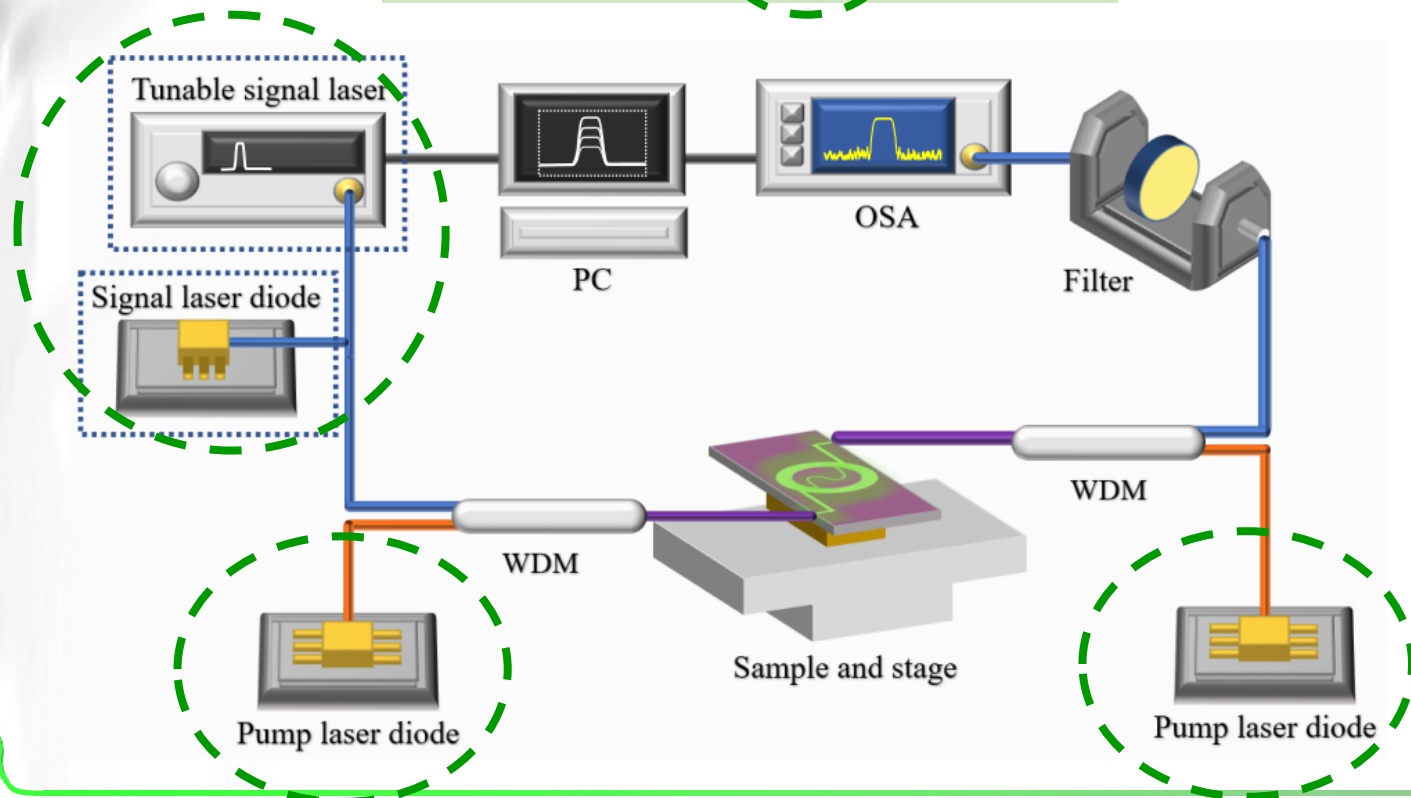


- Chip layout and building blocks
  - $Si_3N_4$  TriPleX input/output couplers
  - 50/50 splitter
  - Reference branch
  - $Si_3N_4 - Al_2O_3$  coupler + amplifier



- Gain with reference branch method
  - Measure amplified signal in amplifier branch ( $T_{on}$ )
  - Measure signal in reference branch ( $T_{ref}$ )

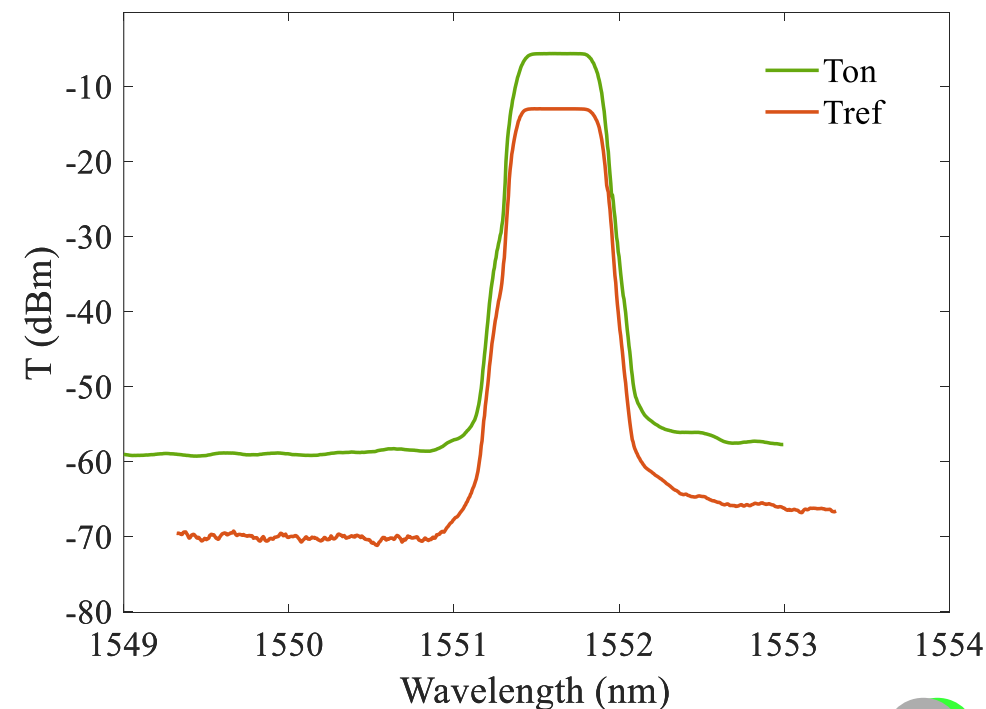
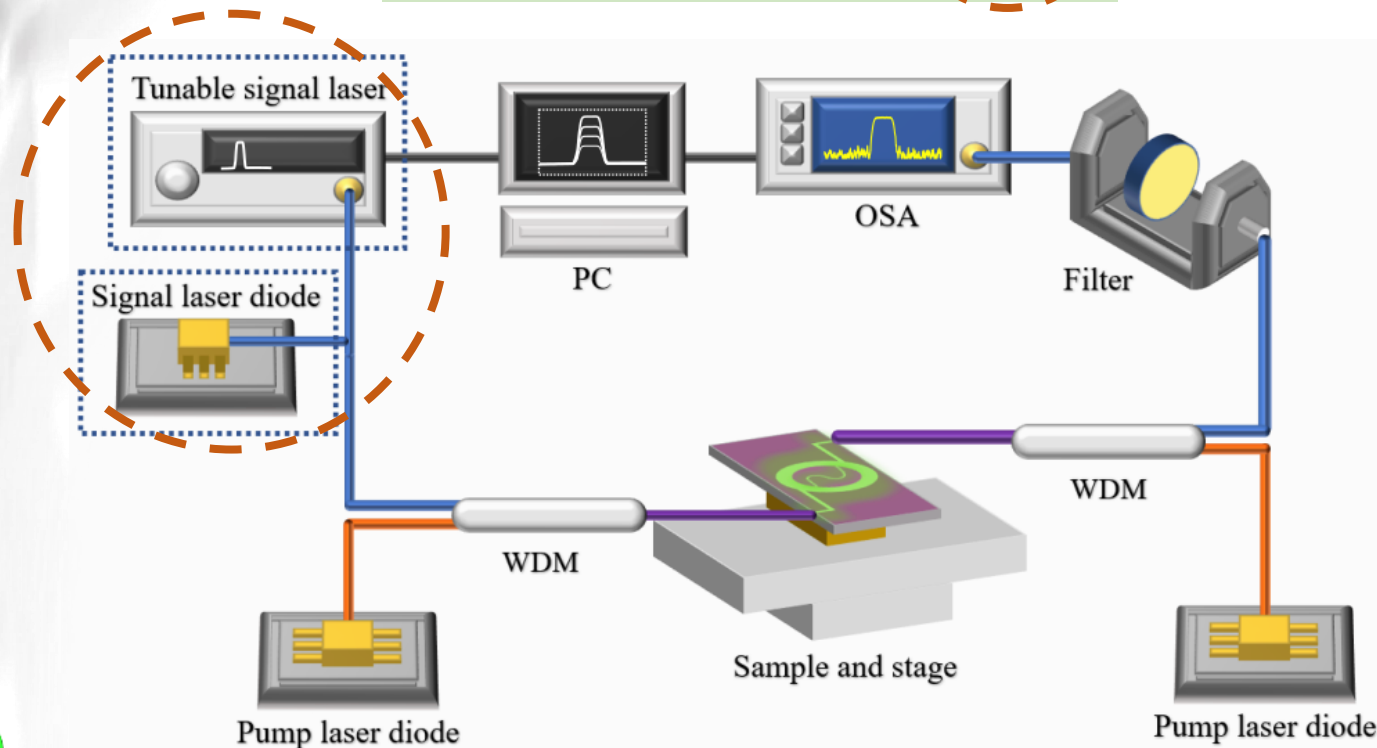
$$g_{global} = T_{on} - T_{ref}$$



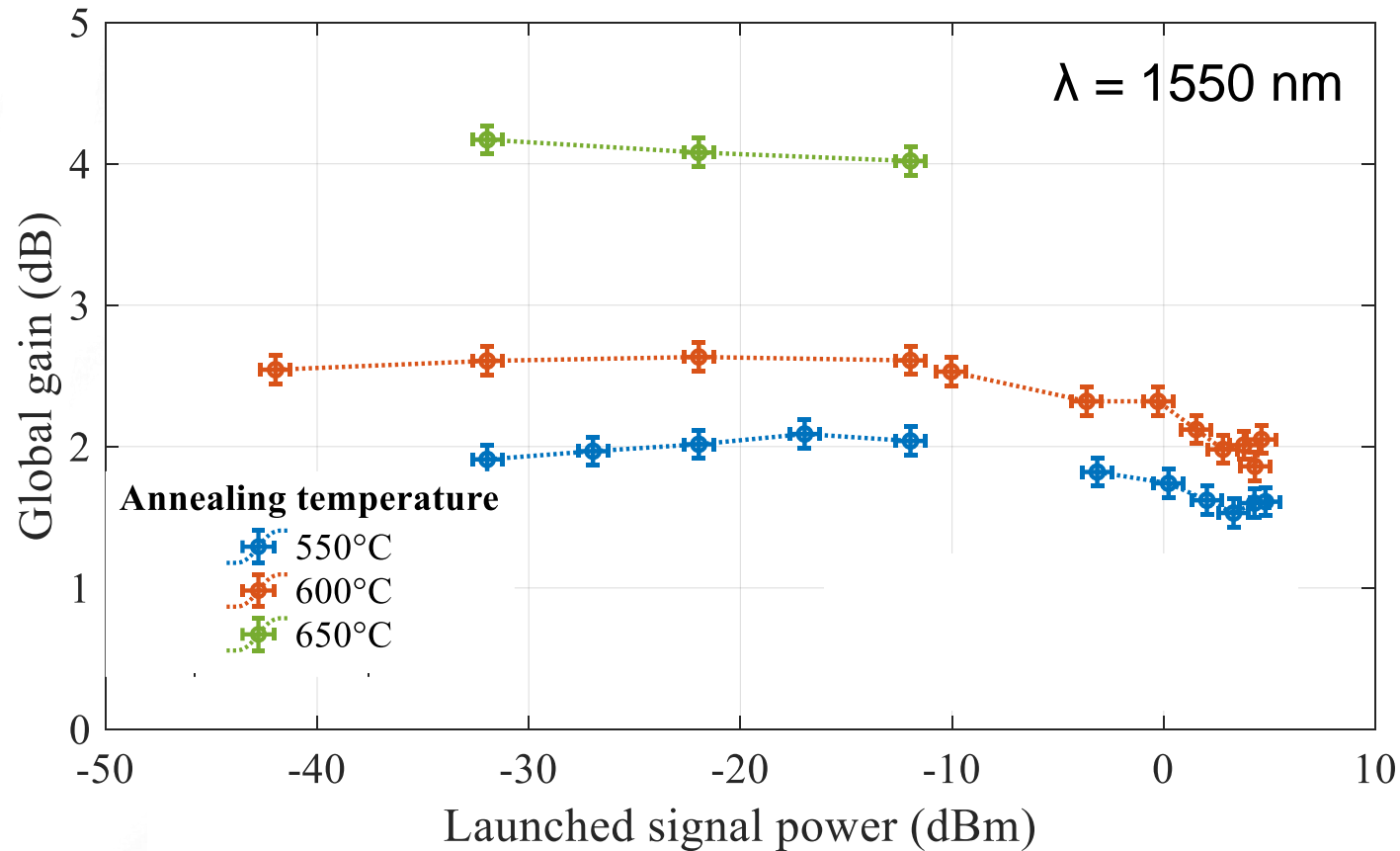


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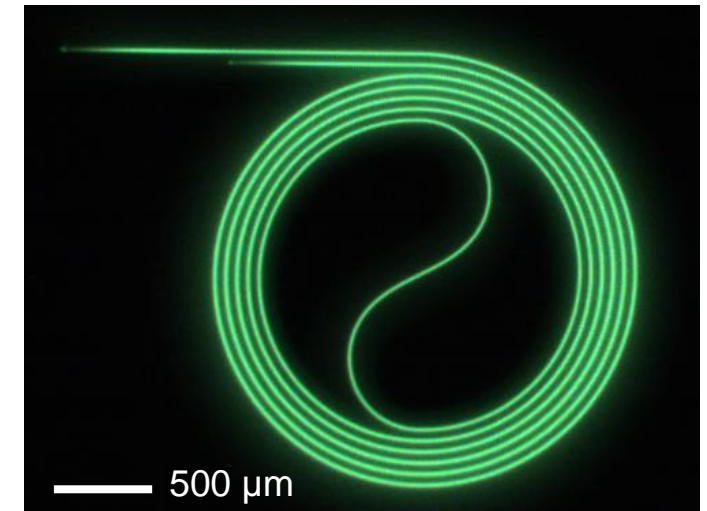
$$g_{global} = T_{on} - T_{ref}$$



- Influence of annealing on the gain
  - Annealing show increase in gain\*



On-chip pump power (~240 mW)

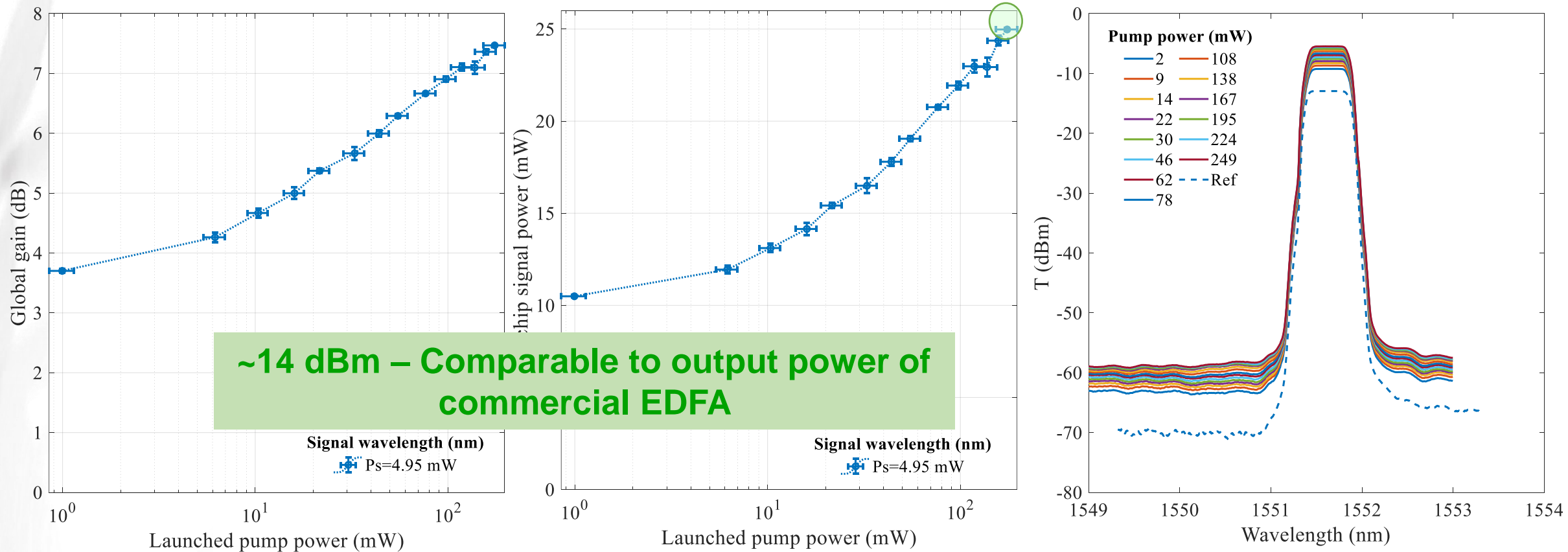


Amplifier length = 3.19 cm

Er<sup>3+</sup> concentration ~1.5x10<sup>20</sup> ion/cm<sup>3</sup>

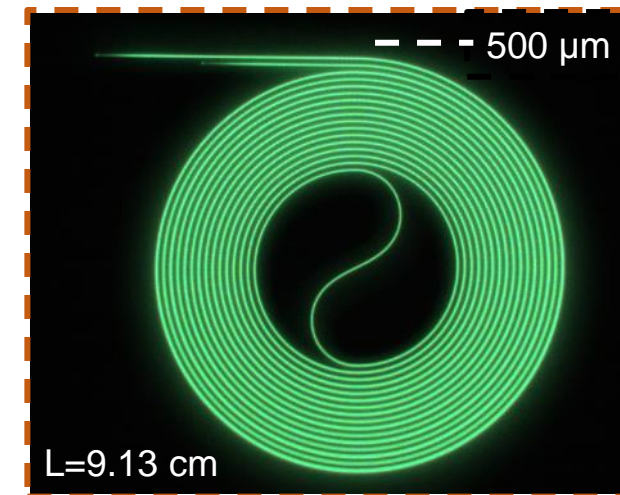
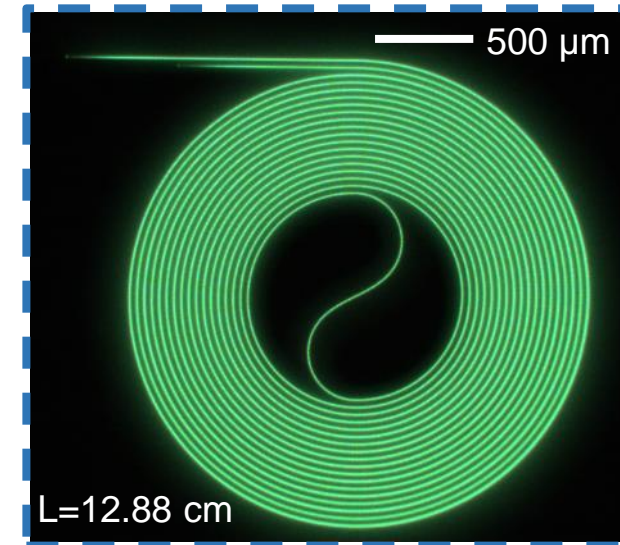
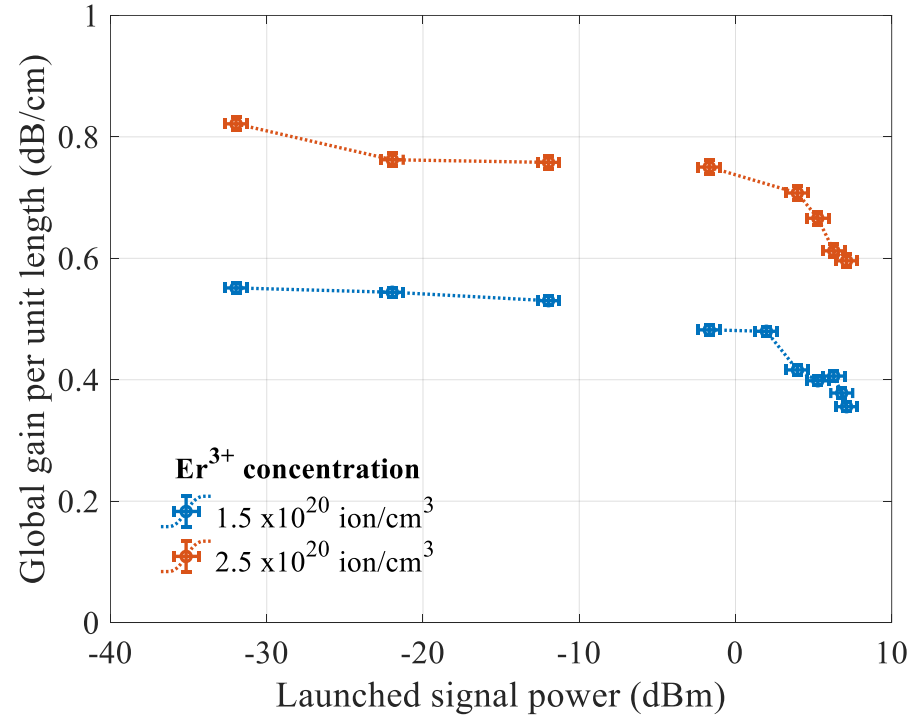
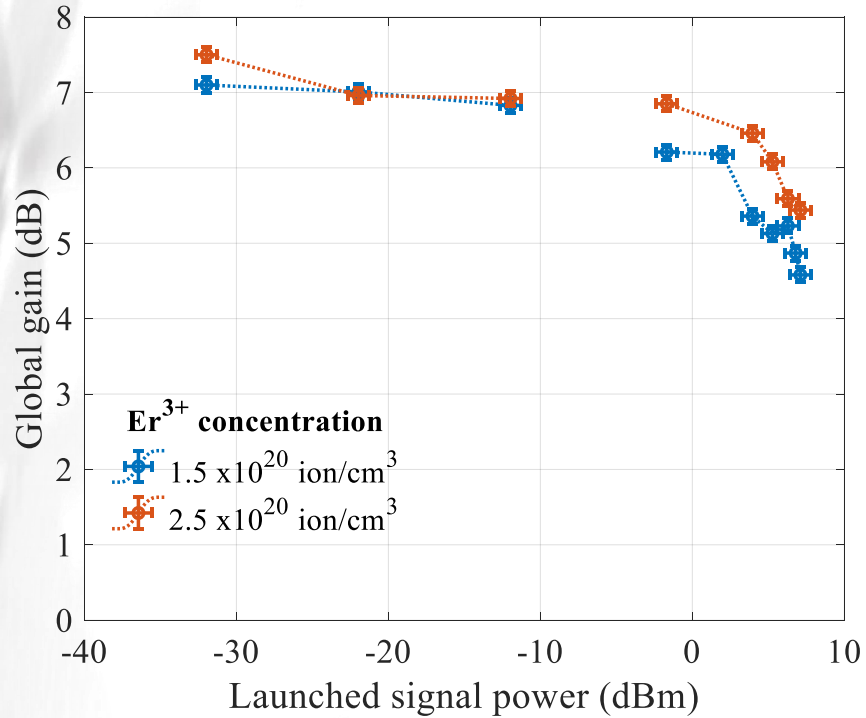
\*variable optimum temperature depending on concentration

- Gain vs pump power



- Gain vs signal power
  - Concentration comparison

$\lambda = 1550 \text{ nm}$



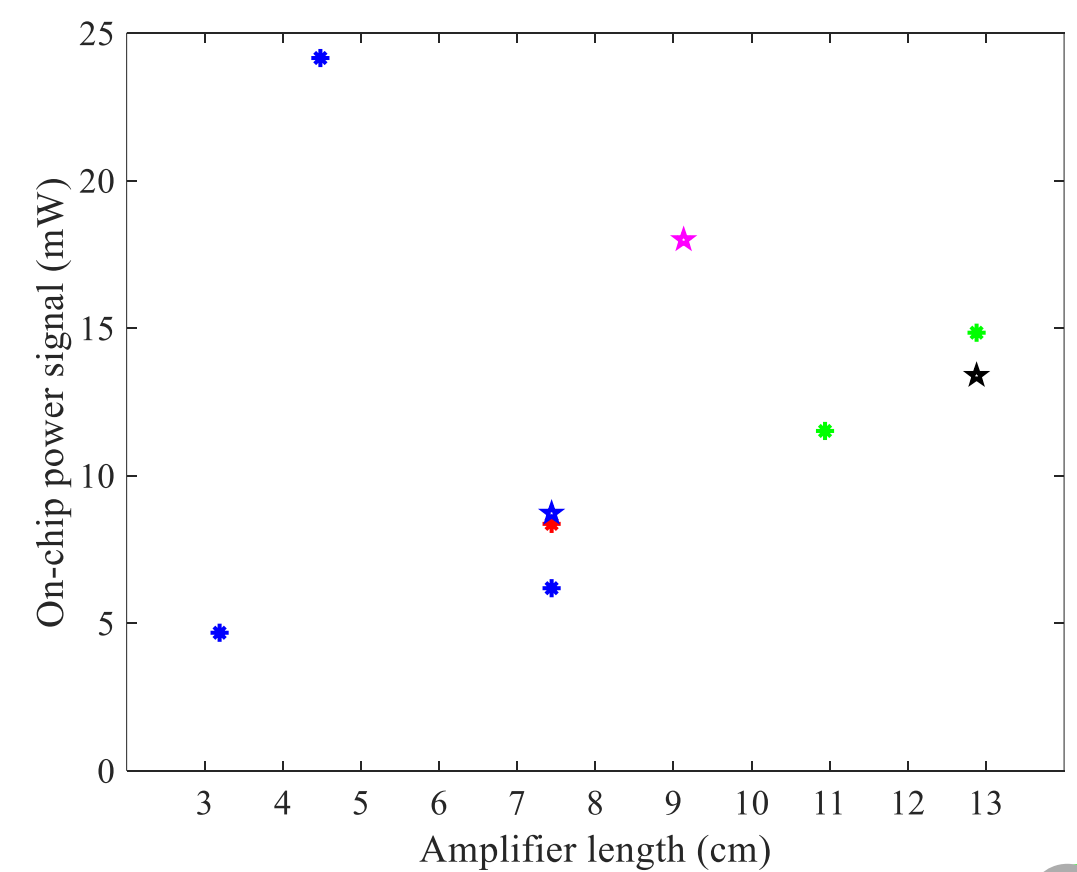
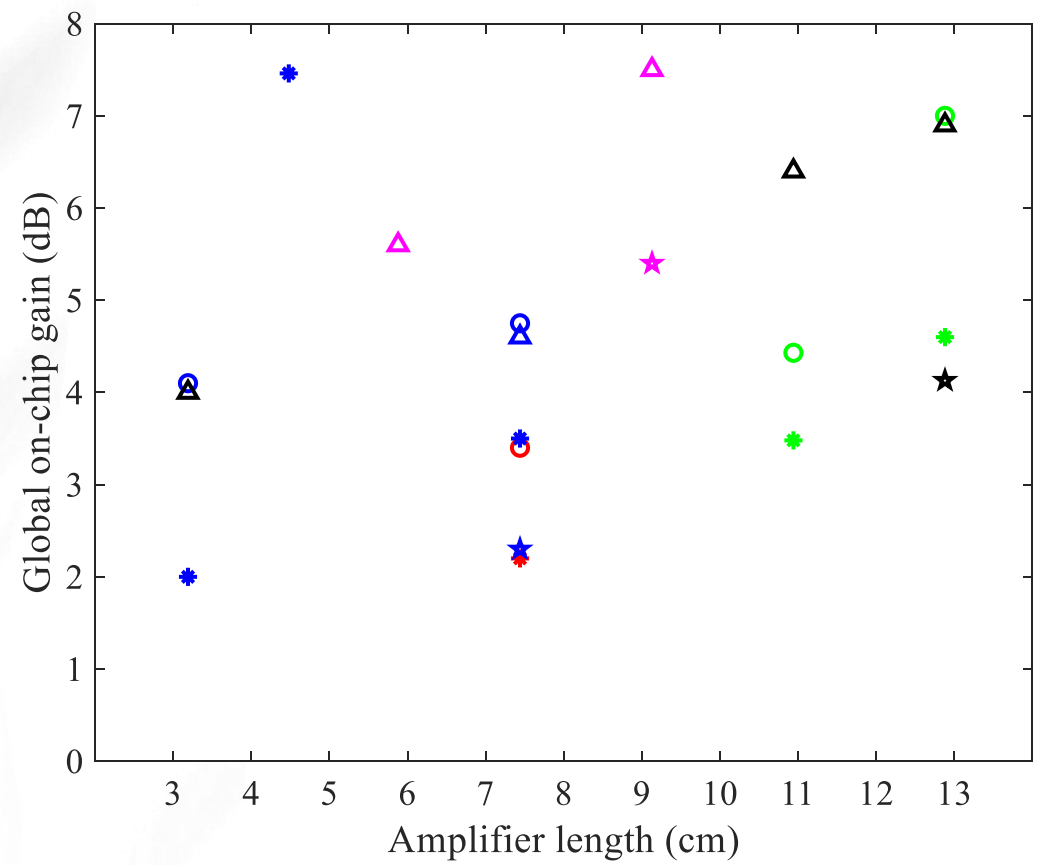
On-chip pump power ~240 mW



- Gain summary
  - Various lengths, widths, concentrations and signal powers

**Launched signal power**

Small signal (~ 1μW)		High* signal (~4.47 mW)	
○	1.6 μm width - Low	●	1.6 μm width - Low
○	1.75 μm width - Low	●	1.75 μm width - Low
○	1.9 μm width - Low	●	1.9 μm width - Low
△	1.6 μm width - Medium	★	1.6 μm width - Medium
△	1.75 μm width - Medium	★	1.75 μm width - Medium
△	1.9 μm width - Medium	★	1.9 μm width - Medium



# Thank you for your attention!

